



承認書

SPECIFICATION FOR APPROVAL

CUSTOMER:

DESCRIPTION:

WIRE WOUND CHIP INDUCTOR

PART NO:

MWI0805LD-TIA系列

CUST. PART NO:

REV. NO.

A0

DRAWING		
PREPARED	CHECKED	APPROVED
邹声平	卢嘉良	曾凡强
DATE:	2025/5/1	

CUSTOMER APPROVE



东莞市铭易轩电子科技有限公司

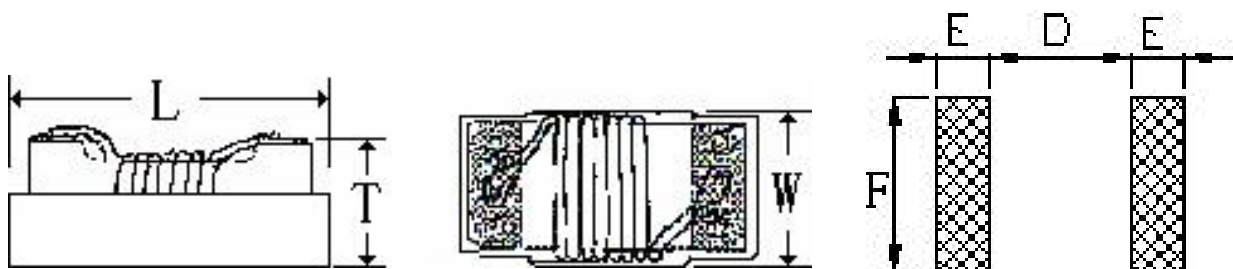
DongGuan Ming Yixuan Electronic Technology Co., LTD

地址: 广东省东莞市大朗镇景泰路20号VV大厦

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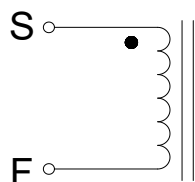
网址: <http://www.dgmingyixuan.com>

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1. SHAPE & DIMENSION (UNIT:mm)


Recommended patterns

L	W	T	E	F	D
2.4 Max.	1.73 Max.	1.52 Max.	1.02 Typ.	1.78 Typ.	0.76 Typ.

2. SCHEMATIC

3. PART NUMBERING SYSTEM

MWI	0805	LD	2R2	M	S	T	-	HF
1	2	3	4	5	6	7		8

- PRODUCT SYMBOL (产品代号)
- DIMENSIONS (规格尺寸)
- MATERIAL (芯片类型)
- INDUCTANCE (电感量)
- TOLERANCE (公差) : K $\pm$ 10%; M $\pm$ 20%
- TERMINAL (端电极材料) : S-锡端头
- PACKAGING (包装方式) : T-编带盘装; B-散装
- E.P. (环保) : LF—Lead Free HF—Halogen Free FP—Red Phosphor Free

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4. ELECTRICAL CHARACTERISTICS

No.	Part Number	L	Freq	Q	SRF	Rdc±30%	Isat	Irms
		(uH)	(MHz)	(Typ.)	(MHz)Typ.	(Ω)Max.	(mA)Typ.	(mA)Typ.
1	MWI0805LD1R0MST-TIA-HF	1	1	12	250	0.14	1100	1200
2	MWI0805LD2R2MST-TIA-HF	2.2	1	12	100	0.18	750	900
3	MWI0805LD4R7MST-TIA-HF	4.7	1	12	50	0.32	530	550
4	MWI0805LD8R2MST-TIA-HF	8.1	1	12	35	0.50	430	460
5	MWI0805LD100MST-TIA-HF	10	1	12	35	0.55	420	450

Test remarks

- (1). All test data is referenced to 25 °C ambient.
- (2). Isat: DC current at which inductance drops approximate 30% from its value without current,
- Irms: DC current that causes the temperature rise ($\Delta T \leq 40^{\circ}\text{C}$) from 25°C ambient.

5. GENERAL SPECIFICATION

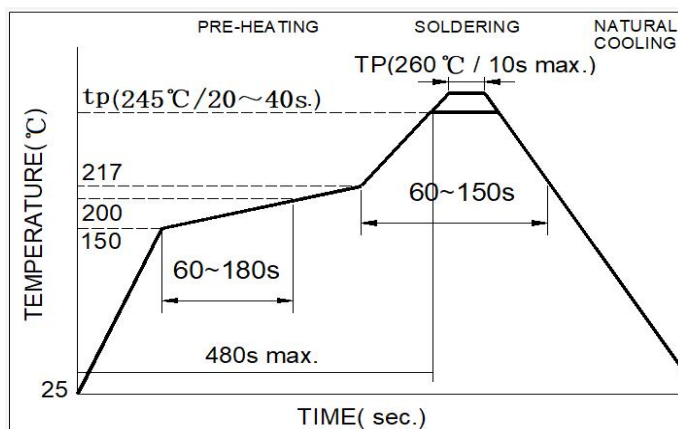
- (1). Operating temp.: -40°C ~ +85°C (Including self-generated heat).
- (2). Storage temp.: -10°C ~ +40°C R.H.:60% Max.
- (3). Moisture sensitivity level (MSL) 1
- (4). Recommended products should be used within 12 months from the date of delivery
- (5). The part temperature (ambient + temp rise) should not exceed 85 °C under worst case operating conditions. Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.

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6. SOLDERING CONDITIONS

Figure 1. Re-flow Soldering (Lead Free)



Note:

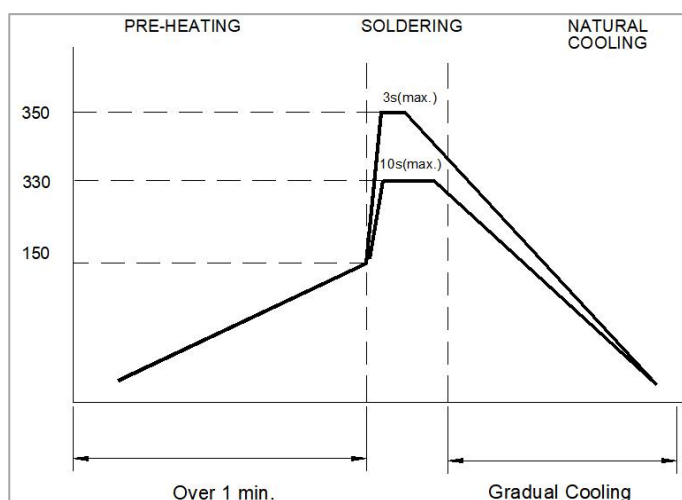
Preheat circuit and products to 150°C

260°C tip temperature (Max)

Reflow times: no more than 2 times

Solder paste thickness: the best 0.08mm is ,but max is 0.1mm

Figure 2. Hand Soldering



Note:

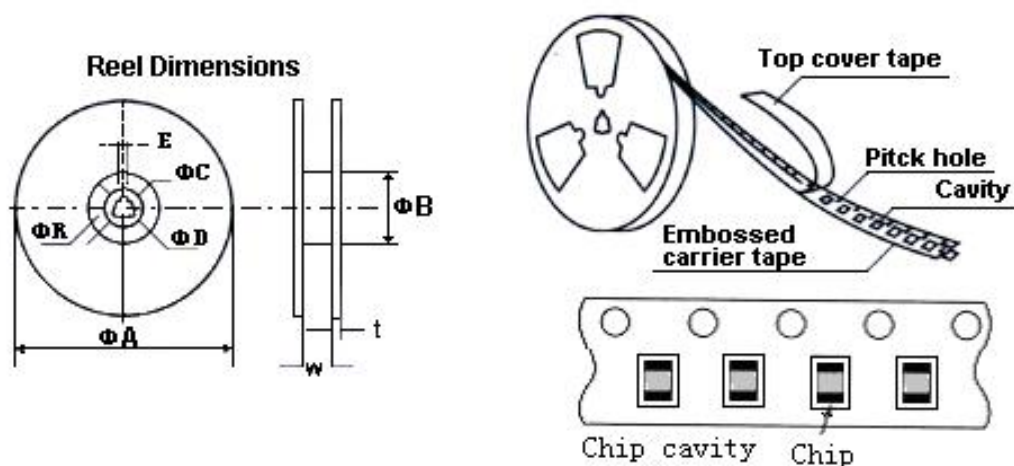
Use a 20 watt soldering iron with tip diameter of 1.0mm

Limit soldering time to 3 sec.

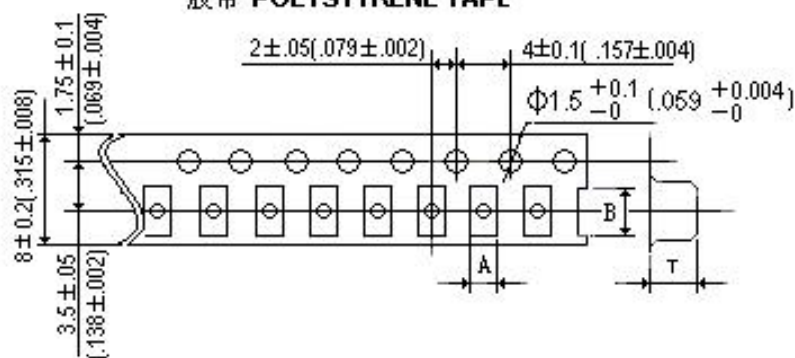
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7. PACKAGE SPECIFICATION (unit: mm)



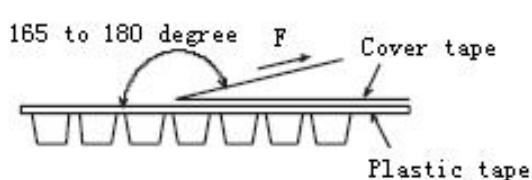
胶带 POLYSTYRENE TAPE



Peeling off force

Pull strength
0402~1210:20g~80g

Speed of peeling off:
300mm/min±10%



		A	B	T
胶带	0805	1.85	2.4	1.45

Type	ΦA	ΦB	ΦC	ΦD	E	W	t
0805	178	60	13	21	2	8.4	2

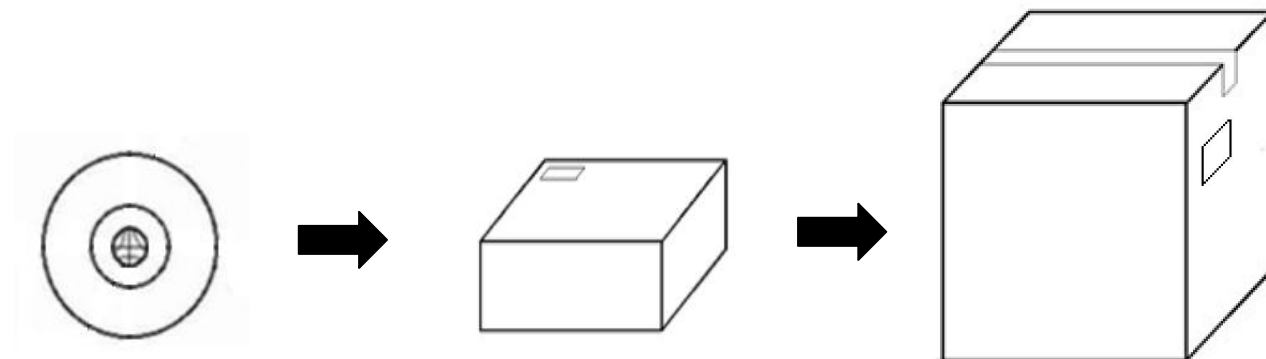
包装数量(PACKAGING QUANTITY): 2000Pcs/盘

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8. Package Specifications

Inside Box And Outside Carton



卷轴数量 每卷:2000PCS	→	内盒包装数量 每盒四盘, 共8000 PCS	→	外箱包装数量 小箱6盒, 共48000 PCS 中箱8盒, 共64000 PCS 大箱10盒, 共80000 PCS
		内盒包装尺寸 20.3*19.3*5.5cm	→	外箱包装尺寸 小箱, 40.6*23*19.7cm 中箱, 41*22*26cm 大箱, 41*22*33cm

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